SN54ABT651...JT PACKAGE SN74ABT651...DB, DW, NT, OR PW PACKAGE

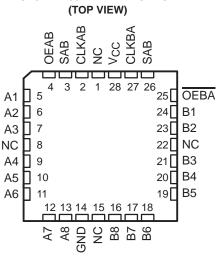
SCBS083E - JANUARY 1991 - REVISED APRIL 1998

- State-of-the-Art *EPIC-*II*B*[™] BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Multiplexed Real-Time and Stored Data
- Inverting Data Paths
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

These devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. The select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT651 devices.

(TOP VIEW)								
CLKAB SAB OEAB A1 A2 A3 A4 A5 A5 A6 A7 A8 GND	1 2 3 4 5 6 7 8 9 10 11 12	24 23 22 21 20 19 18 17 16 15 14 13] V _{CC}] CLKBA] <u>SBA</u>] OEBA] B1] B2] B3] B4] B5] B6] B7] B8					
SN54ABT651 FK PACKAGE								



NC - No internal connection

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs, regardless of the select- or enable-control pins. When SAB and SBA are in the real-time transfer mode, it also is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all the other data sources to the two sets of bus lines are at high impedance, each set remains at its last state.

To ensure the high-impedance state during power up or power down, \overline{OEBA} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver (B to A). OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver (A to B).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 1998, Texas Instruments Incorporated

SCBS083E - JANUARY 1991 - REVISED APRIL 1998

description (continued)

The SN54ABT651 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT651 is characterized for operation from -40°C to 85°C.

	FUNCTION TABLE								
		INPU ⁻	rs			DAT	a I/o	OPERATION OR FUNCTION	
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	OPERATION OR FUNCTION	
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation	
L	Н	Ŷ	\uparrow	Х	Х	Input	Input	Store A and B data	
Х	Н	Ŷ	H or L	Х	Х	Input	Unspecified [†]	Store A, hold B	
н	Н	\uparrow	\uparrow	Х‡	Х	Input	Output	Store A in both registers	
L	Х	H or L	\uparrow	Х	Х	Unspecified [†]	Input	Hold A, store B	
L	L	\uparrow	\uparrow	Х	x‡	Output	Input	Store B in both registers	
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus	
L	L	Х	H or L	Х	Н	Output	Input	Stored B data to A bus	
Н	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus	
н	Н	H or L	Х	Н	Х	Input	Output	Stored A data to B bus	
н	L	H or L	H or L	Н	Н	Output	Output	Stored A data to B bus and stored B data to A bus	

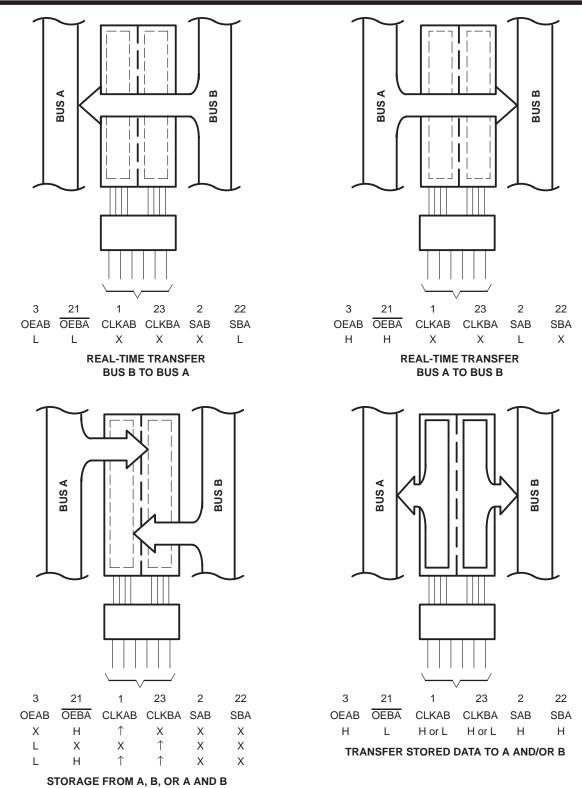
[†] The data output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

[‡] When select control is low, clocks can occur simultaneously if allowances are made for propagation delays from A to B (B to A) plus setup and hold times. When select control is high, clocks must be staggered to load both registers.





SCBS083E - JANUARY 1991 - REVISED APRIL 1998



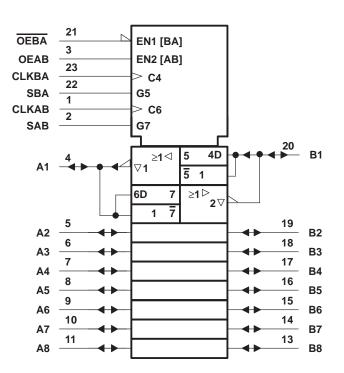
Pin numbers are for the DB, DW, JT, NT, and PW packages.

Figure 1. Bus-Management Functions



SCBS083E - JANUARY 1991 - REVISED APRIL 1998

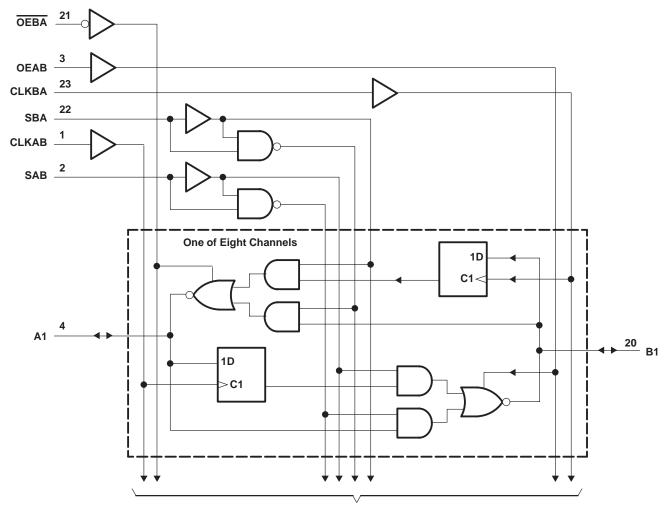
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, and PW packages.



SN54ABT651, SN74ABT651 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS SCBS083E – JANUARY 1991 – REVISED APRIL 1998



To Seven Other Channels

Pin numbers shown are for the DB, DW, JT, NT, and PW packages.

logic diagram (positive logic)



SCBS083E - JANUARY 1991 - REVISED APRIL 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

$ \begin{array}{llllllllllllllllllllllllllllllllllll$	V to 7 V to 5.5 V . 96 mA 128 mA -18 mA -50 mA 104°C/W 81°C/W 67°C/W
PW package 1	
Storage temperature range, T _{stg}	to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT651		SN74A	UNIT	
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	EW	2		V
VIL	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	Vcc	0	VCC	V
ЮН	High-level output current	C,	-24		-32	mA
IOL	Low-level output current	202	48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	32	5		5	ns/V
Т _А	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused pins (control or I/O) of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SCBS083E - JANUARY 1991 - REVISED APRIL 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			T _A = 25°C			SN54ABT651		SN74ABT651		
					TYP†	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		V _{CC} = 4.5 V,	lı = -18 mA			-1.2		-1.2		-1.2	V	
		V _{CC} = 4.5 V,	I _{OH} = –3 mA	2.5			2.5		2.5			
Veri		V _{CC} = 5 V,	I _{OH} = -3 mA	3			3		3		V	
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				v	
		VCC = 4.3 V	I _{OH} = -32 mA	2*					2			
Vei		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100			2			mV	
L.	Control inputs	V _{CC} = 5.5 V,	$V_{I} = V_{CC}$ or GND			±1		1		±1	μA	
łı	A or B ports	VCC = 5.5 V,	VI = VCC OL GIND			±100		±100		±100	μΑ	
IOZH‡		V _{CC} = 5.5 V,	V _O = 2.7 V			50	4	50		50	μΑ	
IOZL [‡]		V _{CC} = 5.5 V,	$V_{O} = 0.5 V$			-50	20	-50		-50	μΑ	
loff		$V_{CC} = 0,$	VI or VO ≤ 4.5 V			±100	90			±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50	49	50		50	μA	
IO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high			250		250		250	μA	
ICC		$I_{O} = 0,$	Outputs low			30		30		30	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			250		250		250	μA	
∆ICC¶		$V_{CC} = 5.5 V$, One inp Other inputs at V_{CC} of				1.5		1.5		1.5	mA	
Ci	Control inputs	VI = 2.5 V or 0.5 V			6						pF	
Cio	A or B ports	V _O = 2.5 V or 0.5 V			7.5						pF	

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5$ V.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 ¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

			= 5 V, 25°C	SN54A	BT651	SN74ABT651		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency		125		125		125	MHz
tw	Pulse duration, CLK high or low	4		4	N.M	4		ns
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		~ 3		3		ns
t _h	Hold time, A or B after CLKAB \uparrow or CLKBA \uparrow	0		0		0		ns



SCBS083E - JANUARY 1991 - REVISED APRIL 1998

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

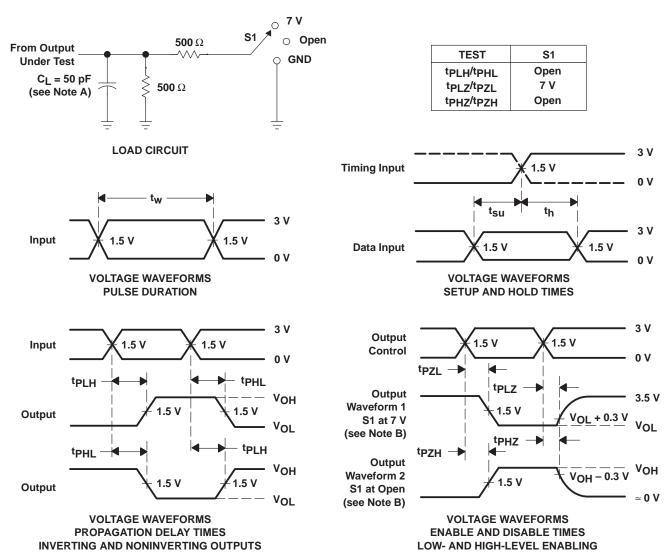
PARAMETER	FROM	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT651		SN74ABT651		UNIT
	(INPUT)	(001201)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			125			125		125		MHz
^t PLH	CLKBA or CLKAB	A or B	2.2	4	5.1	2.2	5.9	2.2	5.6	ns
^t PHL	CLKBA UI CLKAB	AUB	1.7	4	5.1	1.7	5.9	1.7	5.6	115
^t PLH	A or B	B or A	1.5	4	5.1	1.5	6.4	1.5	6.2	ns
^t PHL	AUB	BOIA	1.5	3.3	4.6	1.5	5.6	1.5	5.4	115
^t PLH		SAB or SBA [†] A or B	1.5	4	5.1	1.5	6.8	1.5	6.5	ns
^t PHL	SAB OF SBAT		1.5	3.6	4.9	1.5	6.2	1.5	5.9	115
^t PZH	OEBA A	1.3	3.6	4.6	1.3	5.9	1.3	5.8	ns	
tPZL	OEBA	A	2.5	5.7	6.8	2.5	8.9	2.5	8.5	115
^t PHZ	OEBA	А	1.5	3.2	4.5	9.5	6.2	1.5	5	ns
^t PLZ	OEBA	А	1.5	3	3.8	Q 1.5	4.3	1.5	4.1	115
^t PZH	OEAB	В	1.8	4.3	6.1	1.8	6.7	1.8	6.5	ns
^t PZL		0	2.9	5.5	6.5	2.9	7.6	2.9	7.4	115
^t PHZ	OEAB	В	1.5	3.3	4.5	1.5	6.5	1.5	5.5	
^t PLZ		0	1.5	3.4	4.4	1.5	5.2	1.5	5.1	ns

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SCBS083E - JANUARY 1991 - REVISED APRIL 1998



PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ABT651DBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
SN74ABT651DBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT651DBRE4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT651DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT651DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT651DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT651DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT651NSR	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT651NSRE4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT651NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ABT651NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address:

Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated